

ABSTRACT

A passive component is realized on-die by fabricating a first conductor from either a layer of interconnect metal comprising copper or aluminum and being between approximately 1.0 micron and approximately 2.0 microns thick, or from a layer of under bump metal comprising either copper or aluminum and being between approximately 2.0 microns to approximately 5.0 microns thick. Following, a first isolation layer is formed over the first conductor. A second conductor having at least one external pad and comprising under bump metal is next fabricated over the first isolation layer. The second conductor can be fabricated substantially directly above the first conductor, for example. Thereafter, a second isolation layer having a hole over the external pad of the second conductor is formed over the second conductor. Subsequently, a bump attach site is fabricated at the hole in the second isolation layer over the external pad of the second conductor.

1005438-121901  
TOTAL SHEETS